

DIGITAL AUDIO PLAYER YP-30S

SERVICE Manual

DIGITAL AUDIO PLAYER



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1. Precautions

1-1 Static electricity sense device

Some semi-conductor parts may be easily damaged due to static electricity.

These elements are generally called as static electricity sense device (ESD). Typically examples of EST include IC, some transistor and chip element for semi-conductor with electrical field effect.

The following methods should be used to reduce damage of elements occurred due to static electricity:

- 1. Contact and emit all the grounding objects with static electricity from your body before handling with elements for semi-conductor or devices with elements for semi-conductor. You should purchase and use static electricity arm rings or commercially available. You should remove it due to potential shock before supplying power to the device under test.
- 2. You should place appliance on the conductive surface like aluminum film to prevent that static electricity is accumulated or the device is disclosed outside after removing electrical appliance with the ESD device.
- 3. You should use only soldering iron that is ground when soldering the ESD device.
- 4. Minimize physical operation when handling with the ESD device for replacement without packing (Otherwise, namely friction between cloth fibers or lifting of the foot from the carpet floor may cause static electricity enough to damage the ESD device).

1-2 Cautions for Safety

- 1. To remove dust from cabinet, use a dry cloth without using liquid and aerosol cleaner.
- 2. You should not use attachments not recommended by the company. Otherwise, it may cause critical damage.
- 3. You should not use this product near water such as bathtub, swimming pool or lake etc.
- 4. Power supply: A type of battery as displayed on the label should be only used.
- 5. You should not put any object or liquid into product. Otherwise, it may cause failure or mal-operation.
- 6. If replacement material is required, service engineer should use materials with the same standard. The use of non-standardized materials may cause failure of product.

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2. Specifications

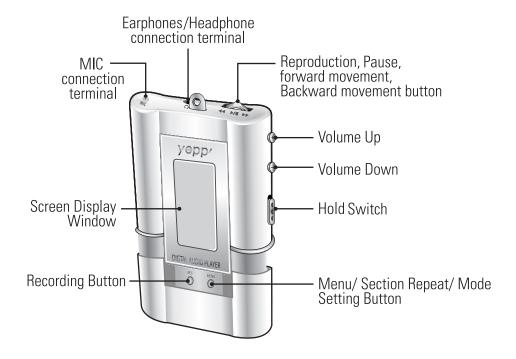
Standards and design may be changed without notice and related weight and dimensions are only approximate.

Power	1.5V (1EA of AAA cell)		
Playing Time	Lasts 5 hours(based on Alkaline cell)		
Memory capacity	64MB		
Dimensions (WxHxD) / Weight	44 x 65 x 14.5 mm/34g		
Material of case	Plastic / Aluminum		
File transfer speed	Max. 7 Mbps (USB)		
Earphones output Power	5mW (16 Ω earphone)		
Ratio of signal to noise	85dB with 20KHz LPP		
Scope of output frequency	20Hz — 20KHz		
Processor	18MHz, 20bit RISC		
Temperature characteristics	-5 ~ 35°C		

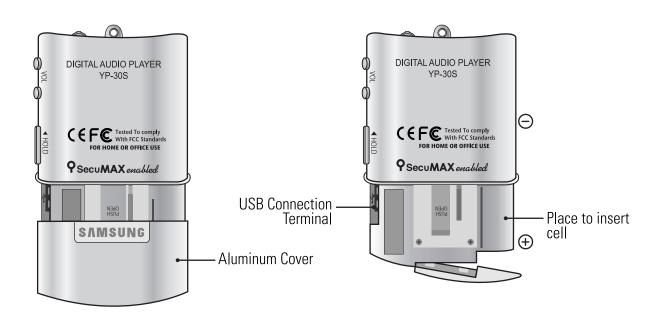
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3. Parts Description

Front Side

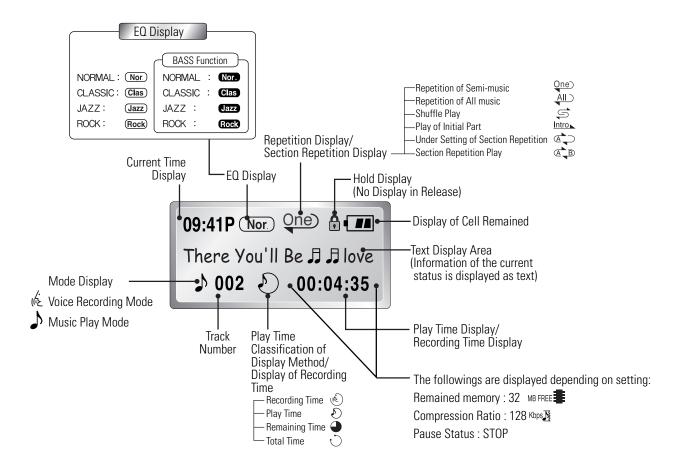


Rear Side



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Screen Display Window



4. Mass-production Initialization Program

4-1 About Mass-production Initialization Program

Program for test and product initialization is provided as separate software in service of this product. This program is not provided to customers and is only designed to use good product inspection and initialization of the ASS'Y PCB obtained from the service center.

4-1-1 Method to supply program

Always perform downloading since this program is not provided as a separate diskette but is distributed via YP-30S SVC Manual Sub-Chapter of **ITSELF System**.

4-1-2 Environment for using program

- (1) IBM compatible PC (PII 233 or more is recommended)
- (2) WINDOWS 98SE/ME/2000
- (3) USB Interface
- (4) Supporting 16bits Color or more and using Video Card
- (5) HDD 5Mbyte or more

4-1-3 Program Function

- (1) Downloading FONT, ICON, LOGO
- (2) Testing Download, Delete, Format
- (3) Downloading Sample Song
- (4) Saving UID

4-1-4 Method to install program

- (1) Execute downloaded program (YP30MASS. Exe)
- (2) Execute installation in accordance with guide of a dialog box.
- (3) Program (yepp Mass Program.exe) is installed on the desktop if installation is completed.

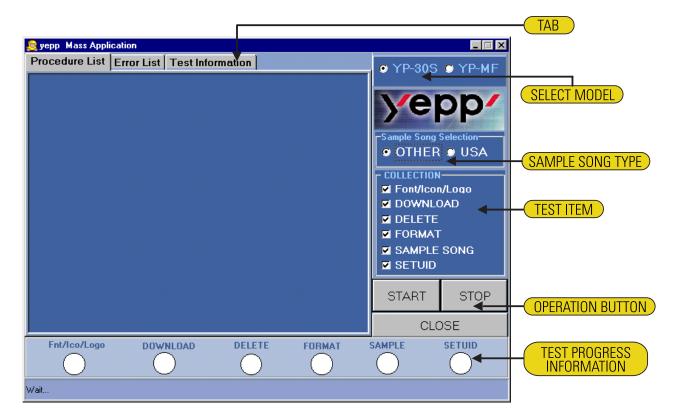
4-1-5 Method to use program

ASS'Y PCB obtained from the service center is not initialized and subject to good product inspection. Please execute as follows for good product inspection and initialization of the obtained ASS'Y.

- (1) Connect ASS'Y PCB of YP 30S to PC via the USB cable.
- (2) After connecting YP-30S to PC, wait 1 minute for YP-30S to format itself.
- (3) No USB communication is done when YP-30S is in clock display mode. Please change to general mode by pressing the (►/■) button.
- (4) Execute program (yepp Mass Program.exe) installed on the basic screen.
- (5) Select all the test items (all are basically selected).
- (6) Click START from the operation button.
- (7) Good product inspection and initialization are successfully completed if a pop-up window called PASS.
- (8) You can view saved contents if clicking the pop-up window called PASS and then clicking the Test Information TAB.

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4-2 Explanation of Mass-production Initialization Program



1. TAB

If clicking each tab, you can see the relevant contents.

- (1) Procedure List
 - -. Test progress information message is output.
- (2) Error List
 - -. Error message occurred during test progress is output.
- (3) Test Information
 - -. Result information is output after completing test.

2. SELECT MODEL (model selection)

- (1) YP-30S
 - -. For YP-30S (selected for this product)
- (2) YP-MF
 - -. For YP-MF series

3. SAMPLE SONG TYPE

- (1) OTHER
 - -. Music file to be initially saved among products released in area except for USA.
 - -. Music files at "\text{\text{WMUSIC\text{\text{W}}}kor\text{\text{\text{W}}}" where program is installed.
 - -. File name: "Yepp-1 groove.mp3", "Yepp-2 funk.mp3"

- (2) USA
 - -. Music file to be initially saved among products released in USA.
 - -. Music files at "₩MUSIC₩eng₩" where program is installed.
 - -. File name: "Yepp-1 groove.mp3", "Yepp-2 funk.mp3"
- 4. Test item (explanation)

Select items to test.

- (1) Font/Icon/Logo
 - -. Ascii Font, Icon, Default Logo, User Logo download check box
- (2) DOWNLOAD
 - -. Download test check box (file download for test, not for consumer)
- (3) DELETE
 - -. Delete test check box
- (4) FORMAT
 - -. Format test check box
- (5) SAMPLE SONG
 - -. Sample song download check box (basic file provided to consumers)
- (6) SETUID
 - -. Check box to register UID

*All items are basically checked (select the only relevant check box if necessary)

5. Operation button

Execute the selected test item.

- (1) START
 - -. Perform test for only .
- (2) STOP
 - -. Suspend test during test.
- (3) CLOSE
 - -. Complete test application.

Test progress information

- 1. Circle is filled with blue if no error occurs in the selected test items.
- 2. Circle is filled with red if error occurs in the selected test items.

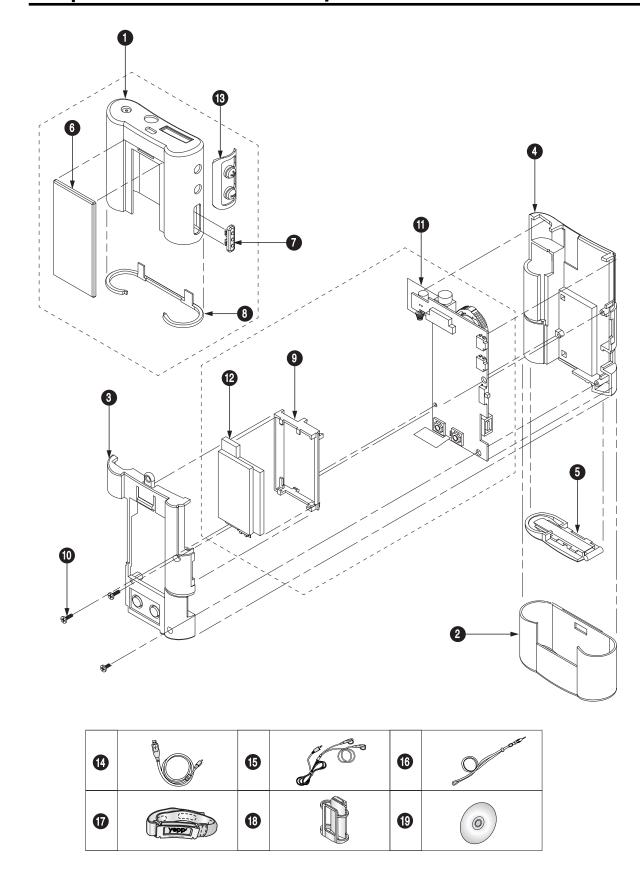
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5. Troubleshooting Guide

Status of Non-conforming	Cause	Point of Repair	
Poor power connection	Poor contact of PCB's battery(+) terminal	Replace battery(+) terminal plate.	
Poor switch	Poor key (SW1 — SW6) contact	Replace the relevant switch.	
No back-light ON	Poor LCD contact	Replace LCD.	
Poor display or No display (forming of stripe, partial dark)	Poor LCD	Replace LCD.	
	No initialization	Execute initialization program.	
Black screen in display of FONT and LOGO	Poor initialization work	Execute initialization program.	
Poor USB communication	Poor computer	- Test in comparison with other YP-30S set - Test in comparison with other computer	
(perform test sequentially)	Poor USB cable	- Test in comparison with other USB cable	
	Soldering of USB port	- Ensure soldering status	

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6. Exploded View and Disassembly Order



NO	Code-No	Description; Specification			
0	AH64-01376A	CABINET-TOP;YP-30S,ANODIZING,AL,0.7T			
2	AH97-00789A	ASSY-CASE BOTTOM; ASSY, YP-30S			
3	AH97-00790A	ASSY-FRAME TOP; ASSY, YP-30S			
4	AH97-00791A	ASSY-FRAME BOTTOM; ASSY, YP-30S			
5	AH97-00792A	ASSY-COVER BATTERY; ASSY, YP-30S			
6	AH64-01407A	WINDOW-LCD; YP-30S, ACRYL, 1.5			
7	AH64-01379A	KNOB-HOLD; YP-30S, ABS			
8	AH64-01382A	DECORATION-RING; YP-30S, ABS			
9	AH61-00790A	HOLDER-LCD; YP-30S, ABS			
0	6003-001257	SCREW-TAPTITE; PH, +, B, M1, L, L6.5, NI PLT, SW			
0	AH92-01100A	ASSY PCB-MIC; YP-30S, ONE-BOARD (For 64MB YP-30S)			
•	AH92-01382A ASSY PCB-32MB-ONE-BOARD; YP-30S(For 32MB YP-30S/CT)				
®	AH07-00059A	LCD; UG-12T14-FGHT X-A, YP-30S, -, 32X4			
13	AH64-01381A	KNOB-VOLUME; YP-30S, ABS			
•	AH39-00301A	CABLE FORM; YD-150B, YP-MF64,4P, 1.2M, -,-,PVC, BEIGE, 4PX1200MM,-,USB CABLE			
15	AH59-01014A	SPEAKER SYSTEM; YP-30S, YH-30SGU, 0.22V,0.2			
16	AH61-00845A	HANGER-NECKLES; YP-30S			
•	AH63-00380A	BAND; -,-,PVC, YP-30S,DOMESTIC(For Asia)			
	AH63-00328A	BAND-ARM; -,-,PVC,YP-30S(Except Asia)			
13	AH97-00844A	ASSY-CRADLE; -,YP-30S			
19	AH80-00028A	INSTALL-MFN CD; YP-30S,30S CD, CD, KOR-CD			

- Disassembly and assembly method
- 1. Remove No 2 while pressing No. "PUSH OPEN".
- 2. Remove No. 7
- 3. Remove No. 6
- 4. Pull and remove No. while pressing the upper part of No. (take care so that No. switch would not be pressed).
- 5. Carefully extend No. 3 a little, and lift up and remove it along with the main body
- 6. Remove No. 🐠
- 7. Lift No. 10 up (separate it No. 3, No. 4, No. 5 and No. 10).
- 8. Lift the No. LCD connector up.
- 9. After lifting No. 20 up from the connector lightly, apply heat with a soldering iron on the soldering part.
- 10. Separate No. 9 and No. 12.
- Cautions in assembling
- 1. After ensuring No. 3 is properly placed at No. 1, insert frame (without care, SW2 or SW3 may be damaged).
- 2. Since a flaw may occur if lifting No. up from the lower part and then inserting it, lower it down from the upper part for insertion.
- 3. Securely insert No. 2 and No. 3 into the No. 3 connector and then fix them at the PCB. (Back light soldering condition of LCD: 360°C, within 2 seconds)
- 4. When properly placing No. (4, -), adjust orientation accurately.

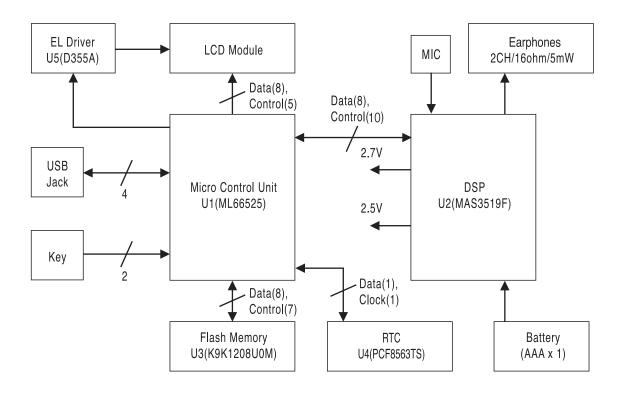
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7. Electrical Parts List

Loc. No.	Code No.	Description ; Specification F	Remark	Loc. No.	Code No.	Description ; Specification Rem
		· · · · ·				· · ·
В3	3301-001419	CORE-FERRITE BEAD;AB,220ohm,1.6x0.8x0.8m		R19	2007-000120	R-CHIP;680ohm,5%,1/16W,DA,TP,1608
BT2	2409-001042	C-EDL;200000UF,3.3V,3.3V,0.15MA,TP,6		R2	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C10	2203-000726	C-CERAMIC, CHIP; 3.9nF, 10%, 50V, X7R, TP, 1608		R20	2007-000125	R-CHIP;3.9Kohm,5%,1/16W,DA,TP,1608
C13	2203-000125	C-CERAMIC,CHIP;1.2nF,10%,50V,X7R,TP,1608		R21	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C14	2203-000125	C-CERAMIC,CHIP;1.2nF,10%,50V,X7R,TP,1608		R22	2007-000090	R-CHIP;10K0HM,5%,1/16W,DA,TP,1608
C15	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R23	2007-000123	R-CHIP;1.5Kohm,5%,1/16W,DA,TP,1608
C16	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R24	2007-000123	R-CHIP;1.5Kohm,5%,1/16W,DA,TP,1608
C17	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R25	2007-000123	R-CHIP;1.5Kohm,5%,1/16W,DA,TP,1608
C18	2203-001103	C-CERAMIC,CHIP;6.8nF,10%,50V,X7R,TP,1608		R26	2007-000113	R-CHIP;33ohm,5%,1/16W,DA,TP,1608
C19	2203-001103	C-CERAMIC,CHIP;6.8nF,10%,50V,X7R,TP,1608		R29	2007-000090	R-CHIP;10KOHM,5%,1/16W,DA,TP,1608
C2	2404-000293	C-TA,CHIP;220UF,10%,6.3V,GP,TP,7343H		R3	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C20	2404-001159	C-TA,CHIP;100UF,10%,6.3V,GP,TP,6032		R30	2007-000090	R-CHIP;10K0HM,5%,1/16W,DA,TP,1608
C21	2404-001159	C-TA,CHIP;100UF,10%,6.3V,GP,TP,6032		R31	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C22	2203-000257	C-CERAMIC,CHIP;10nF,10%,50V,X7R,TP,1608		R33	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C3 C30	2404-000335 2203-000315	C-TA,CHIP;3.3uF,20%,16V,GP,TP,3216 C-CERAMIC,CHIP;0.12nF,5%,50V,NP0,TP,1608		R34 R4	2007-000090 2007-000090	R-CHIP;10K0HM,5%,1/16W,DA,TP,1608 R-CHIP;10K0HM,5%,1/16W,DA,TP,1608
C32	2203-000313	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R40	2007-000090	R-CHIP;22ohm,5%,1/16W,DA,TP,1608
C33	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R41	2007-000071	R-CHIP;1.5Kohm,5%,1/16W,DA,TP,1608
C34	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R42	2007-000123	R-CHIP;22ohm,5%,1/16W,DA,TP,1608
C35	2404-001020	C-TA,CHIP;10uF,20%,10V,GP,TP,3216,3.2		R43	2007-000109	R-CHIP;1Mohm,5%,1/16W,DA,TP,1608
C36	2404-000151	C-TA,CHIP;1uF,20%,16V,-,TP,3216,-		R44	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C38	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R45	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C39	2203-005005	C-CERAMIC, CHIP; 100nF, 10%, 16V, X7R, TP, 1608		R46	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C4	2404-000293	C-TA,CHIP;220UF,10%,6.3V,GP,TP,7343H		R47	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C40	2203-005005	C-CERAMIC, CHIP; 100nF, 10%, 16V, X7R, TP, 1608		R48	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C41	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R49	2007-000090	R-CHIP;10K0HM,5%,1/16W,DA,TP,1608
C42	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R5	2007-000124	R-CHIP;2.2Kohm,5%,1/16W,DA,TP,1608
C43	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R50	2007-000125	R-CHIP;3.9Kohm,5%,1/16W,DA,TP,1608
C46	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R51	2007-000125	R-CHIP;3.9Kohm,5%,1/16W,DA,TP,1608
C47	2203-005005	C-CERAMIC,CHIP;100nF,10%,16V,X7R,TP,1608		R52	2007-000125	R-CHIP;3.9Kohm,5%,1/16W,DA,TP,1608
C52	2203-000315	C-CERAMIC,CHIP;0.12nF,5%,50V,NP0,TP,1608		R53	2007-000090	R-CHIP;10K0HM,5%,1/16W,DA,TP,1608
C54	2203-000315	C-CERAMIC,CHIP;0.12nF,5%,50V,NP0,TP,1608		R54	2007-000090	R-CHIP;10K0HM,5%,1/16W,DA,TP,1608
C55	2404-000151	C-TA,CHIP;1uF,20%,16V,-,TP,3216,-		R55	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C56 C6	2203-000726 2404-000335	C-CERAMIC,CHIP;3.9nF,10%,50V,X7R,TP,1608		R57 R59	2007-000121	R-CHIP;820ohm,5%,1/16W,DA,TP,1608
C60	2203-000626	C-TA,CHIP;3.3uF,20%,16V,GP,TP,3216 C-CERAMIC,CHIP;0.022nF,5%,50V,NP0,TP,160		R6	2007-000987 2007-001147	R-CHIP;5.6ohm,5%,1/16W,DA,TP,1608 R-CHIP;7.5ohm,5%,1/16W,DA,TP,1608
C61	2203-000020	C-CERAMIC,CHIP;0.007nF,0.25pF,50V,NP0,TP		R60	2007-001147	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608
C62	2203-000257	C-CERAMIC,CHIP;10nF,10%,50V,X7R,TP,1608		R62	2007-000102	R-CHIP;10K0HM,5%,1/16W,DA,TP,1608
C63	2203-000257	C-CERAMIC,CHIP;10nF,10%,50V,X7R,TP,1608		R7	2007-001147	R-CHIP;7.5ohm,5%,1/16W,DA,TP,1608
C64	2203-000998	C-CERAMIC,CHIP;0.047nF,5%,50V,NP0,TP,160		R8	2007-000113	R-CHIP;33ohm,5%,1/16W,DA,TP,1608
C65	2203-000998	C-CERAMIC,CHIP;0.047nF,5%,50V,NP0,TP,160		R9	2007-000113	R-CHIP;33ohm,5%,1/16W,DA,TP,1608
C7	2203-000257	C-CERAMIC,CHIP;10nF,10%,50V,X7R,TP,1608		SW1	3408-001070	SWITCH-SLIDE;5V DC,10mA,-,0FF-<0N>,-
C8	2404-001158	C-TA,CHIP;47uF,10%,6.3V,GP,TP,3528		SW2	3404-001161	SWITCH-TACT;12V DC,50mA,220gf,5.5x4.5x1.
C9	2203-000257	C-CERAMIC,CHIP;10nF,10%,50V,X7R,TP,1608		SW3	3404-001161	SWITCH-TACT;12V DC,50mA,220gf,5.5x4.5x1.
D11	0404-001010	DIODE-SCHOTTKY;MA729,30V,200mA,DSM,TP		SW4	3404-001180	SWITCH-TACT;12V DC,50MA,260GF,5.2X5.2X1.
D12	0404-001010	DIODE-SCHOTTKY;MA729,30V,200mA,DSM,TP		SW5	3404-001180	SWITCH-TACT;12V DC,50MA,260GF,5.2X5.2X1.
D13	0404-001010	DIODE-SCHOTTKY;MA729,30V,200mA,DSM,TP		SW6	3408-001052	SWITCH-SLIDE;5V,0.3A,2P,<0FF-0N>,-
D3	0404-001089	DIODE-SCHOTTKY;RB551V-30,30V,500mA,SOD-3		T1	0406-001128	DIODE-TVS;MLVS-0603-E08,50V,-,-
D4	0404-001089	DIODE-SCHOTTKY;RB551V-30,30V,500mA,SOD-3	3	T2	0406-001128	DIODE-TVS;MLVS-0603-E08,50V,-,-
D5	0404-001010	DIODE-SCHOTTKY;MA729,30V,200mA,DSM,TP		T3	0406-001128	DIODE-TVS;MLVS-0603-E08,50V,-,-
D6	0404-001010	DIODE-SCHOTTKY;MA729,30V,200mA,DSM,TP		T4	0406-001128	DIODE-TVS;MLVS-0603-E08,50V,-,-
D7 D9	0404-001010 0404-001010	DIODE-SCHOTTKY;MA729,30V,200mA,DSM,TP DIODE-SCHOTTKY;MA729,30V,200mA,DSM,TP		T5 U1	0406-001128 0903-001248	DIODE-TVS;MLVS-0603-E08,50V,-,- IC-MICROCONTROLLER;ML66Q525,16BIT,TQFP,1
J1	3722-001605	JACK-PHONE;3P,3.6PI,AG,BLK,-		U2	1204-001881	IC-ENCODER/DECODER;MAS3519F,PLQFP,64P,-,
J2	3708-001630	CONNECTOR-FPC/FC/PIC;15P,0.5MM,SMD-A,-		U3	1107-001280	IC-FLASH MEMORY;9K1208,64Mx8Bit,TSOP,48P
J3	3708-001600	CONNECTOR-FPC/FC/PIC;4P,0.8MM,SMD-A,GOL	n	U4	0909-001031	IC-REAL TIME CLOCK;8563,-,TSSOP,8P,118MI
L1	2703-001864	INDUCTOR-SMD:15UH.20%.6X6X2.8MM		U5	1003-001233	IC-POWER DRIVER:1DDD355AA-M02.MSOP.8P
L2	2703-001864	INDUCTOR-SMD;15UH,20%,6X6X2.8MM		U6	1203-001970	IC-VOLTAGE REGULATOR;-,SOT-89,3P,100MIL
L3	2703-002247	INDUCTOR-SMD;4.7MH,20%,3.8X3.8X2.0		U7	1203-002172	IC-VOL. DETECTOR;80823,SC-82AB,4P,49MIL,
L4	2703-000271	INDUCTOR-SMD;4.7uH,10%,2x1.25x1.25mm		Y1	2802-001168	RESONATOR-CERAMIC;12MHZ,0.5%,TP,3.7X3.1X
L5	2703-000271	INDUCTOR-SMD;4.7uH,10%,2x1.25x1.25mm		Y2	2801-004053	CRYSTAL-SMD;0.032768MHZ,20PPM,28-BCG,7PF
MIC	3003-001062	MIC-CONDENSOR;2V,130UA-50,-42DB+-3DB,2.2) :	Y3	2802-001150	RESONATOR-CERAMIC;18.432MHZ,0.5%,TP,3.2X
Q2	0505-001426	FET-SILICON;IRLML6401,P,-12V,-4.3A,0.05o			AA61-00787A	PLATE-BATTERY; YP-30S, BPS, 0.2T, Au-p
Q3	0504-001048	TR-DIGITAL;-,NPN,100MW,47K,SC-70,TP			AA61-00806A	SPRING-BATTERY;YP-30S,SWC,0.45,-,-,-
R10	2007-000123	R-CHIP;1.5Kohm,5%,1/16W,DA,TP,1608				
R11	2007-000123	R-CHIP;1.5Kohm,5%,1/16W,DA,TP,1608				
R12	2007-000121	R-CHIP;820ohm,5%,1/16W,DA,TP,1608				
R13	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608				
R15	2007-000090 2007-000090	R-CHIP;10K0HM,5%,1/16W,DA,TP,1608 R-CHIP;10K0HM,5%,1/16W,DA,TP,1608				
R16						

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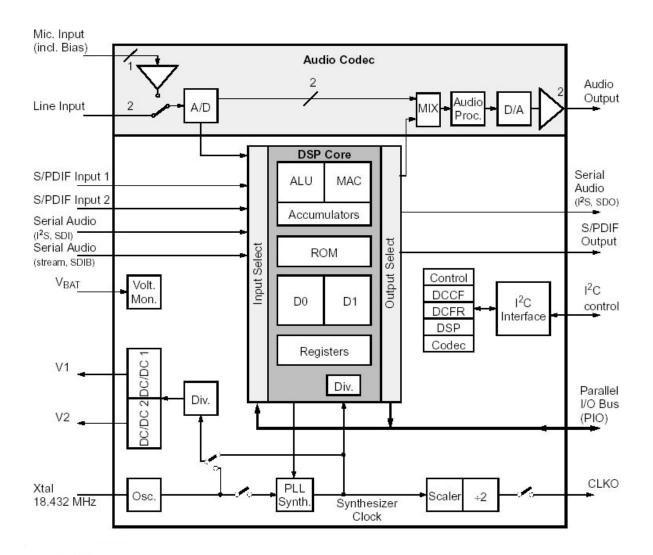
8. Block Diagram



Samsung Electronics 8-1

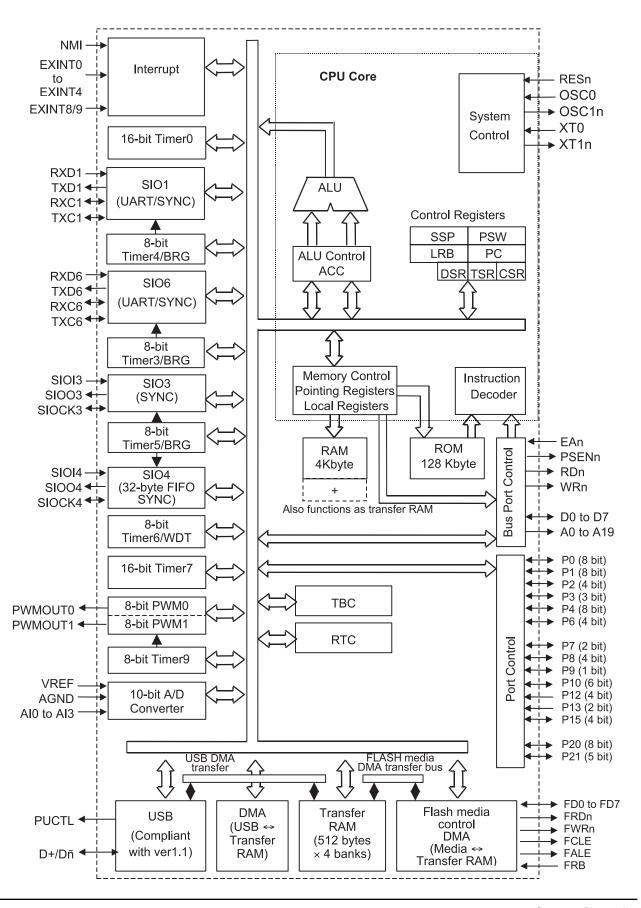
9. Internal Block Diagram of Main IC

9-1 MAS3519



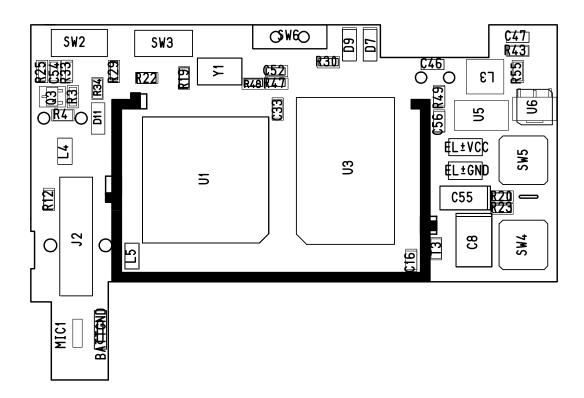
Samsung Electronics 9-1

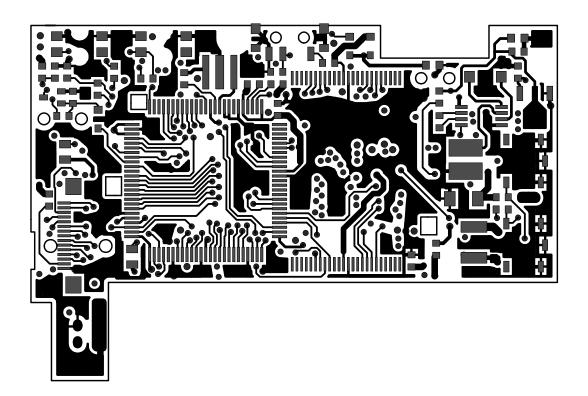
9-2 ML66525



10. PCB Wiring Diagrams

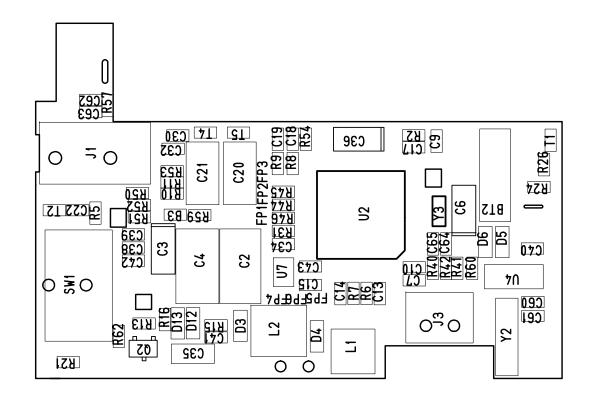
10-1 Component Side

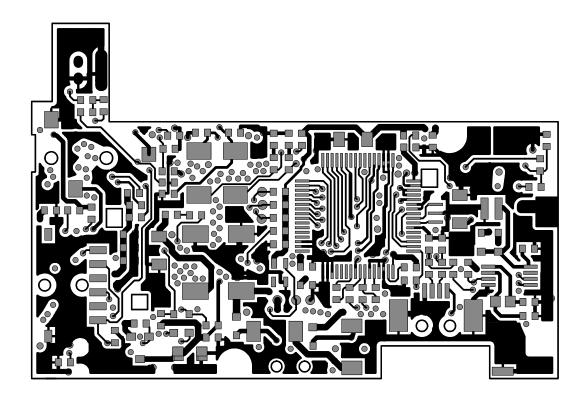




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10-2 Solder Side





11. Schematic Diagram

